



# Product Change Notification

## 103760 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geography location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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# Product Change Notification

**Change Notification #:** 103760 - 00  
**Change Title:** Intel(R) Stacked Chip Scale Package with 32Mb Advanced+ Boot Block Flash and 8Mb SRAM, Added Cypress SRAM, PCN 103760-00, FYI  
**Date of Publication:** December 12, 2003

**Type of Change Notification:**  
FYI - (For Your Information)

**Key Characteristics of the Change:**  
Documentation

## Forecasted Key Milestones:

<b>Date of Qualification Data Availability:</b>	Dec 12, 2003
<b>Date Customer Must be Ready to Receive Post-Conversion Material:</b>	Jan 12, 2004
<b>Date of First Availability of Post-Conversion Material:</b>	Jan 12, 2004

*The date of "First Availability of Post-Conversion Material" is the projected date that a customer may expect to receive the Post-Conversion Materials. This date is determined by the projected depletion of inventory at the time of the PCN publication. The depletion of inventory may be impacted by fluctuating supply and demand, therefore, although customers should be prepared to receive the Post-Converted Materials on this date, Intel will continue to ship and customers may continue to receive the pre-converted materials until the inventory has been depleted.*

## Description of Change to the Customer:

Intel is adding Cypress SRAM to our existing Advanced+ Boot Block Flash Memory product in the 32Mb Stacked Chip Scale Package with 8Mb SRAM.

This will improve product availability and increase production capacity across Intel's assembly fabrication network. This will also enable Intel to more effectively respond to the growing demands for Flash.

SRAMs used with .13 $\mu$  lithography flash die are Samsung .15 $\mu$  and NEC .18 $\mu$ .. Cypress is .15

## Customer Impact of Change and Recommended Action:

Intel does not anticipate any impact to customer applications. There will be no change to the part marking.

Customers must be positioned to accept and use 0.13 $\mu$ m lithography products with all SRAM combinations.

## Products Affected / Intel Ordering Codes:

Pre-Conversion Product Code	Pre-Conversion Spec/ROM	Pre-Conversion MM#
RD38F1020C0ZBL0	N/A	849857
RD38F1020C0ZBL0S	S B48	849855
RD38F1020C0ZBL0S	S B93	849856
RD38F1020C0ZTL0	N/A	849854
RD38F1020C0ZTL0S	S B48	849852
RD38F1020C0ZTL0S	S B93	849853

## Reference Documents / Attachments:

Document:

Location #:

## PCN Revision History:

Date of Revision:

December 12, 2003

Revision Number:

00

Reason:

Originally Published PCN